

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01338	10.0	0.26281
	Silver alloy	Silver (Ag)	7440-22-4	0.00268	2.0	0.05256
	Lead alloy	Lead (Pb)	7439-92-1	0.11777	88.0	2.3127
		Subtotal		0.13383	100	2.62807
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.19584	7.7	43.12
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.42209	12.0	67.2
	Filler	Silica fused	60676-86-0	22.81394	80.0	448
	Carbon Black	Carbon black	1333-86-4	0.08555	0.3	1.68
		Subtotal		28.51742	100	560
Lead Frame	Iron-nickel alloy	Phosphorous (P)	7723-14-0	0.02102	0.03	0.4128
	Iron-nickel alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.75677	1.08	14.8608
	Iron-nickel alloy	Copper (Cu)	7440-50-8	69.22353	98.79	1,359.3504
		Subtotal		70.00132	99.9	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.05311	100.0	20.68
		Subtotal		1.05311	100	20.68
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.05197	100.0	1.02053
		Subtotal		0.05197	100	1.02053
Die		Silicon (Si)	7440-21-3	0.17228	100.0	3.383
		Subtotal		0.17228	100	3.383
Total				99.92993	100	NaN

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